

2N4859/A, 2N4860/A, 2N4861/A N-Channel JFET JAN Equivalent Parts

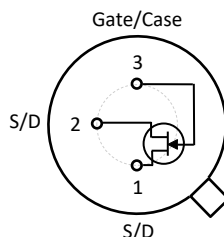
Features

- InterFET [N0132S Geometry](#)
- Low noise: 1.0 nV/√Hz typical
- High gain: 22mS typical
- Low gate leakage: 750fA typical @20V
- High radiation tolerance
- RoHS, REACH, CMR compliant
- Custom test and binning options available
- Edge case SPICE modeling: [InterFET SPICE](#)

InterFET Similar Parts

- 2N3970, 2N4391
- IFN113

TO-18 Bottom View



Built to MIL-PRF-19500

(Source and Drain pins are interchangeable)

Applications

- General: Amplifiers; Switches; Voltage regulators; Oscillators; Signal mixers; Noise generators
- Military/Aero: Radar; Communications; Satellites; Missiles guidance; Hydrophone Pre-Amps
- Medical: Medical imaging systems; Medical monitors and recorders; Ultrasound equipment
- Audio: Tone control circuits; Headphone amplifiers; Audio filters; Electret Microphone

Description

The -30V InterFET 2N4859/A, 2N4860/A, and 2N4861/A JFET's are targeted for very low noise switching applications for mid to high frequency designs. Gate leakages are typically 50pA at room temperatures. The TO-18 package is hermetically sealed and suitable for military applications.

Ordering Information

Part Number	Description	Case	Packaging
2N4859JANequiv;2N4860JANequiv; 2N4861JANequiv	JAN equivalent	TO-18	Bulk
2N4859AJANequiv;2N4860AJANequiv; 2N4861AJANequiv	JAN equivalent	TO-18	Bulk
2N4859JANTXequiv;2N4860JANTXequiv; 2N4861JANTXequiv	JANTX equivalent	TO-18	Bulk
2N4859AJANTXequiv;2N4860AJANTXequiv; 2N4861AJANTXequiv	JANTX equivalent	TO-18	Bulk
2N4859JANTXVequiv;2N4860JANTXVequiv; 2N4861JANTXVequiv	JANTXV equivalent	TO-18	Bulk
2N4859AJANTXVequiv;2N4860AJANTXVequiv; 2N4861AJANTXVequiv	JANTXV equivalent	TO-18	Bulk
2N4859JANSequiv;2N4860JANSequiv; 2N4861JANSequiv	JANS equivalent	TO-18	Bulk
2N4859AJANSequiv;2N4860AJANSequiv; 2N4861AJANSequiv	JANS equivalent	TO-18	Bulk



NOTICE: Please refer to the end of this document for information on product materials, compliance, safety, and legal statements.

Electrical Characteristics

Maximum Ratings (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified)			
Parameters		TO-18	Unit
V_{RGS}	Reverse Gate Source and Gate Drain Voltage	-20	V
I_{FG}	Continuous Forward Gate Current	50	mA
P_D	Continuous Device Power Dissipation ¹	500	mW
P	Power Derating ¹	3.3	mW/ $^\circ\text{C}$
T_J	Operating Junction Temperature	-65 to 175	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 to 175	$^\circ\text{C}$

¹Thermal power dissipation and derating values obtained with gate pin (substrate) thermally connected to pad and/or internal layer.

Static Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified, Highlighted values = A variant)

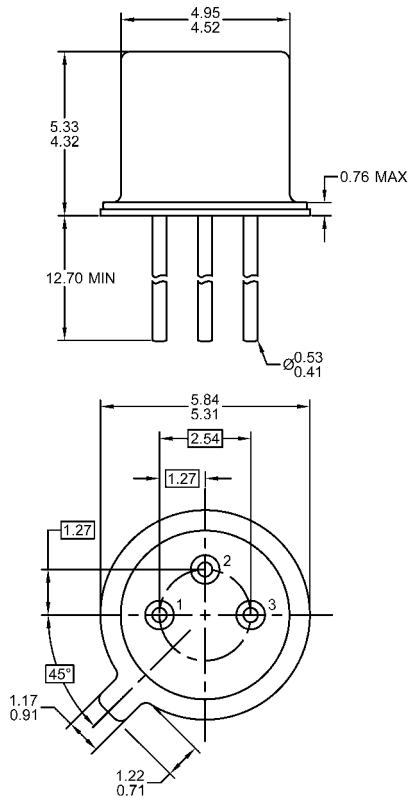
Parameters	Conditions	2N4859/A		2N4860/A		2N4861/A		Unit
		Min	Max	Min	Max	Min	Max	
$V_{(BR)GSS}$	Gate to Source Breakdown Voltage $I_G = -1\mu\text{A}, V_{DS} = 0\text{V}$	-30		-30		-30		V
I_{GSS}	Gate to Source Reverse Current $V_{GS} = -15\text{V}, V_{DS} = 0\text{V}, T_A = 25^\circ\text{C}$ $V_{GS} = -15\text{V}, V_{DS} = 0\text{V}, T_A = 150^\circ\text{C}$		-250 -500		-200 -500		-200 -500	pA nA
$V_{GS(OFF)}$	Gate to Source Cutoff Voltage $V_{DS} = 15\text{V}, I_D = 0.5\text{nA}$	-4	-10	-2	-6	-0.8	-4	V
I_{DSS}	Drain to Source Saturation Current $V_{DS} = 15\text{V}, V_{GS} = 0\text{V}$ (Pulsed)	50		20	100	8	80	mA
$I_{D(OFF)}$	Drain Cutoff Current $V_{DS} = 15\text{V}, V_{GS} = -10\text{V}, T_A = 25^\circ\text{C}$ $V_{DS} = 15\text{V}, V_{GS} = -10\text{V}, T_A = 150^\circ\text{C}$		250 500		250 500		250 500	pA nA
$V_{DS(ON)}$	Drain to Source ON Voltage $V_{GS} = 0\text{V}, I_D = ()$		0.75 (20)		0.5 (10)		0.5 (5)	V mA

Dynamic Characteristics (@ $T_A = 25^\circ\text{C}$, Unless otherwise specified, Highlighted values = A variant)

Parameters	Conditions	2N4859/A		2N4860/A		2N4861/A		Unit
		Min	Max	Min	Max	Min	Max	
$R_{DS(ON)}$	Drain to Source ON Resistance $V_{GS} = 0\text{V}, I_D = 0\text{A},$ $f = 1\text{kHz}$		25		40		60	Ω
C_{iss}	Input Capacitance $V_{DS} = 0\text{V}, V_{GS} = -10\text{V},$ $f = 1\text{MHz}$		18 10		18 10		18 10	pF
C_{rss}	Reverse Transfer Capacitance $V_{DS} = 0\text{V}, V_{GS} = -10\text{V},$ $f = 1\text{MHz}$		8 4		8 3.5		8 3.5	pF
t_d	Turn-On Delay Time $V_{DD} = 10\text{V}, V_{GS(ON)} = 0\text{V}$ $I_{D(ON)} = (), V_{GS(OFF)} = []$		6 5 (20) [-10]		6 6 (10) [-6]		10 8 (5) [-4]	ns (mA) [V]
t_r	Rise Time $V_{DD} = 10\text{V}, V_{GS(ON)} = 0\text{V}$ $I_{D(ON)} = (), V_{GS(OFF)} = []$		3 3 (20) [-10]		4 4 (10) [-6]		10 8 (5) [-4]	ns (mA) [V]
$t_{d(off)}$	Turn-Off Delay Time $V_{DD} = 10\text{V}, V_{GS(ON)} = 0\text{V}$ $I_{D(ON)} = (), V_{GS(OFF)} = []$		25 25 (20) [-10]		50 40 (10) [-6]		100 80 (5) [-4]	ns (mA) [V]

TO-18 Mechanical and Layout Data

Package Outline Data



1. All linear dimensions are in millimeters.
2. Package weight approximately 0.29 grams
3. Bulk product is shipped in standard ESD shipping material
4. Refer to JEDEC standards for additional information.



Compliance and Legal

Environment

InterFET parts follow the latest RoHS Compliance, REACH Compliance, Proposition 65 Statement, TSCA Statement, and Chemical Disposal and Waste Mitigation requirement and guidelines. For more on InterFET's Environmental Commitment please visit

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